

IN THE SPECIFICATION:

Please amend the abstract as follows:

Amended Abstract – Clean Version of Changes Made

a) A new type of suspension circuit electrical bonding pad for electrically and mechanically connecting the magnetic recording head is described. The new type of bonding pad will serve as the joint material as well as the joint interface. Thus, there is no need to apply the conductive material in between the bonding pads and the magnetic recording head terminals, consequently reducing the process leading time and simplifying the magnetic recording head assembly process.

IN THE CLAIMS:

Please amend the claims as follows:

Amended Claims – Clean Version of Changes Made

a250 6. (Amended) A bonding pad for electrically bonding a magnetic head terminal as set forth in claim 2, wherein a bump height for the solder is approximately 50-300 μm , and a bump diameter for the solder is less than 180 μm .

a3 12. (Amended) The disk drive as claim in claim 8, wherein a bump height for the solder is approximately 50-300 μm , and a bump diameter for the solder is less than

180 μm .

13. (Amended) An assemble method for a bonding pad for electrically bonding a magnetic head terminal comprising:

providing a first metal pad on an incoming suspension;

planting a bonding substance onto said first metal pad of said suspension;

subsequently potting a slider on said suspension; and

making a heat treatment for said suspension so that said bonding substance on said first metal pad adheres to a second metal pad of said slider, the bonding substance becoming a solid state.

18. (Amended) The method as claimed in claim 14, wherein a bump height for the solder is approximately 50-300 μm , and a bump diameter for the solder is less than 180 μm .